

### 描述 / Descriptions

SOT-323 塑封封装 硅 PNP 数字三极管。Silicon PNP Digital transistor in a SOT-323 Plastic Package.

### 特征 / Features

内装偏置电阻，简化线路设计，减少元件和制造流程，无卤产品。

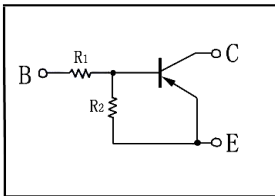
With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process, HF Product.

### 用途 / Applications

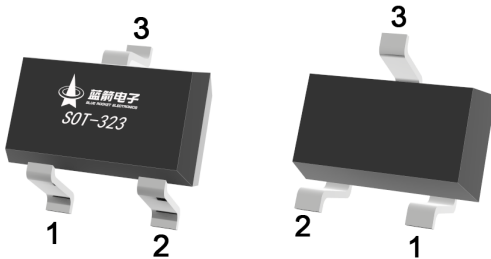
用于开关、反相电路、界面电路以及驱动电路中。

Switching, inverter circuit, interface circuit and driver circuit applications.

### 内部等效电路 / Equivalent Circuit



### 引脚排列 / Pinning



PIN 1 : Base

PIN 2 : Emitter

PIN 3 : Collector

### 放大及印章代码 / hFE Classifications & Marking

Marking	HE11
---------	------

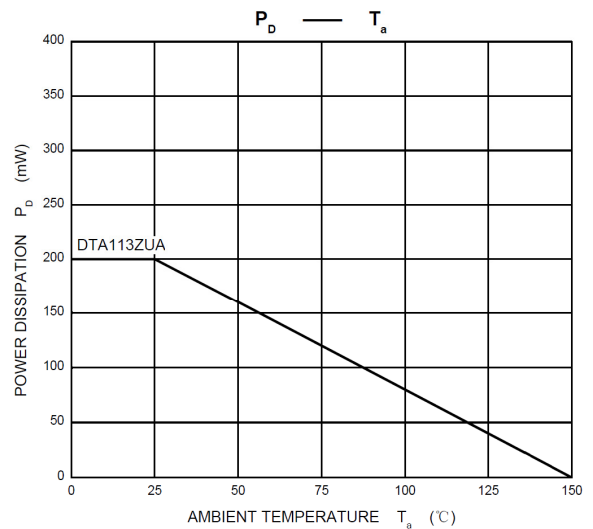
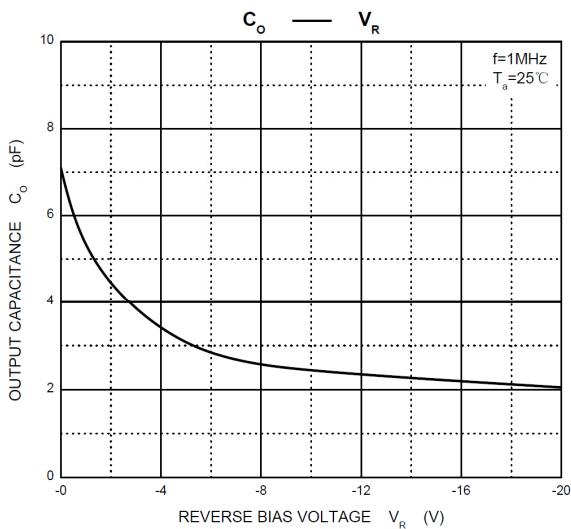
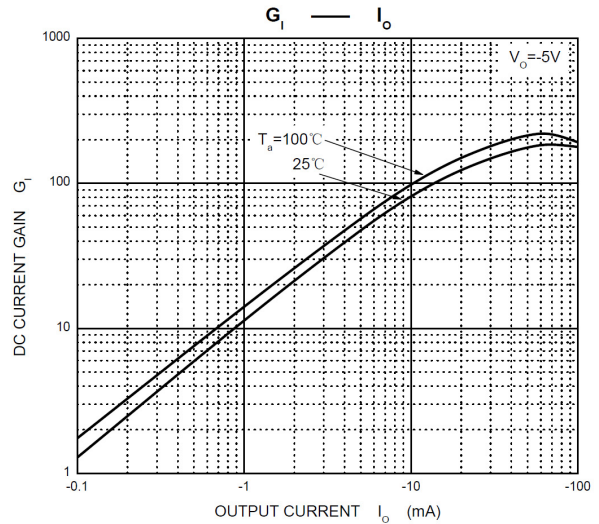
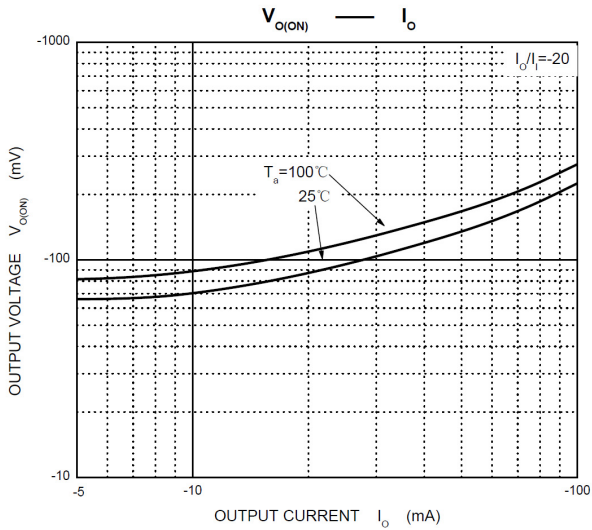
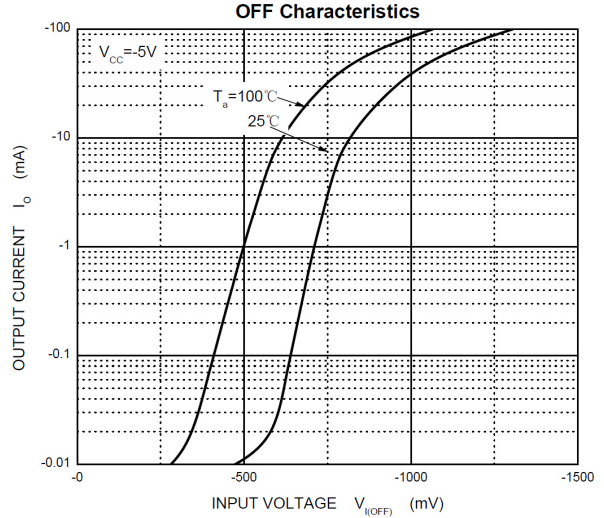
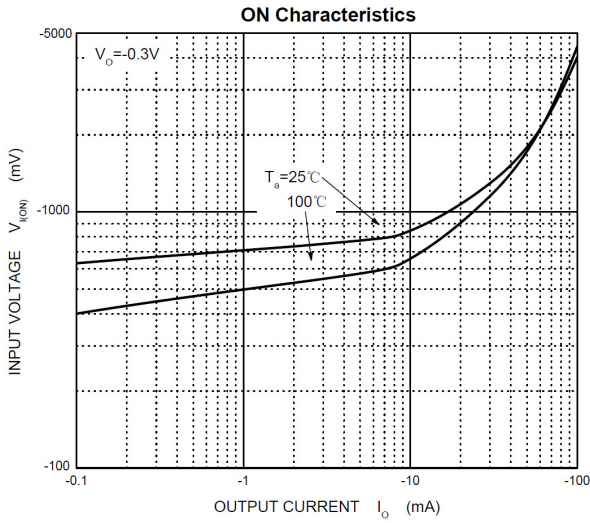
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Supply Voltage	V <sub>CC</sub>	-50	V
Input Voltage	V <sub>IN</sub>	-10	V
		5	V
Output Current	I <sub>O</sub>	-100	mA
Power Dissipation	P <sub>D</sub>	200	mW
Operation Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~150	°C

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Input Voltage	V <sub>I(off)</sub>	V <sub>CC</sub> =-5.0V I <sub>O</sub> =-100μA	-0.3			V
	V <sub>I(on)</sub>	V <sub>O</sub> =-0.3V I <sub>O</sub> =-20mA			-3	V
Output Voltage	V <sub>O(on)</sub>	I <sub>O</sub> =-10mA I <sub>I</sub> =-0.5mA			-0.3	V
Input Current	I <sub>I</sub>	V <sub>I</sub> =-5.0V			-7.2	mA
Output current	I <sub>O(off)</sub>	V <sub>CC</sub> =-50V V <sub>I</sub> =0V			-0.5	μA
DC Current Gain	G <sub>I</sub>	V <sub>O</sub> =-5.0V I <sub>O</sub> =-5mA	33			
Transition Frequency	f <sub>T</sub>	V <sub>O</sub> =-10V I <sub>O</sub> =-5.0mA f=100MHz		250		MHz
Resistance1	R <sub>1</sub>		0.7	1	1.3	KΩ
Resistance Ratio	R <sub>2</sub> /R <sub>1</sub>		8	10	12	

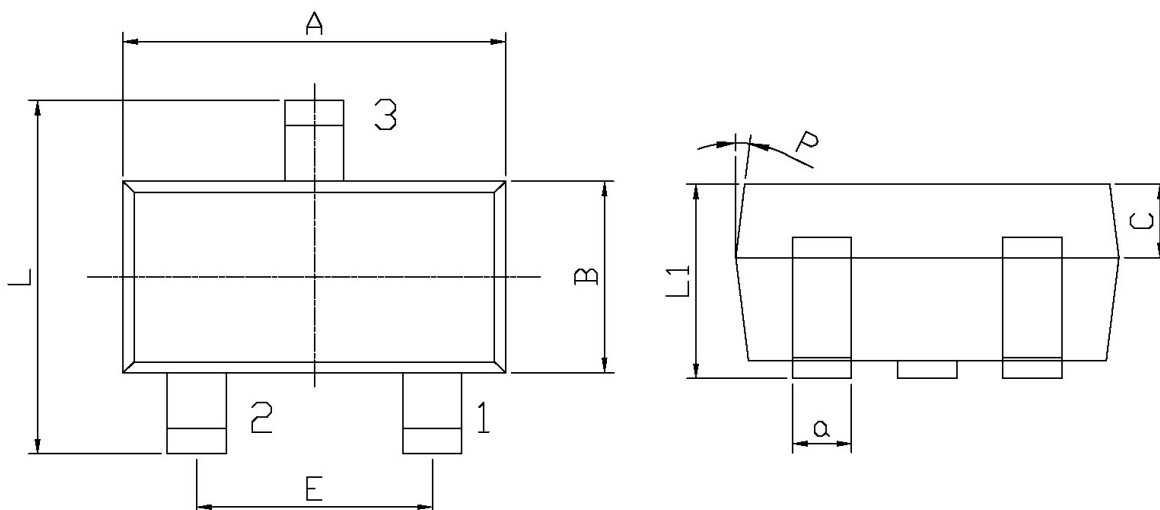
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

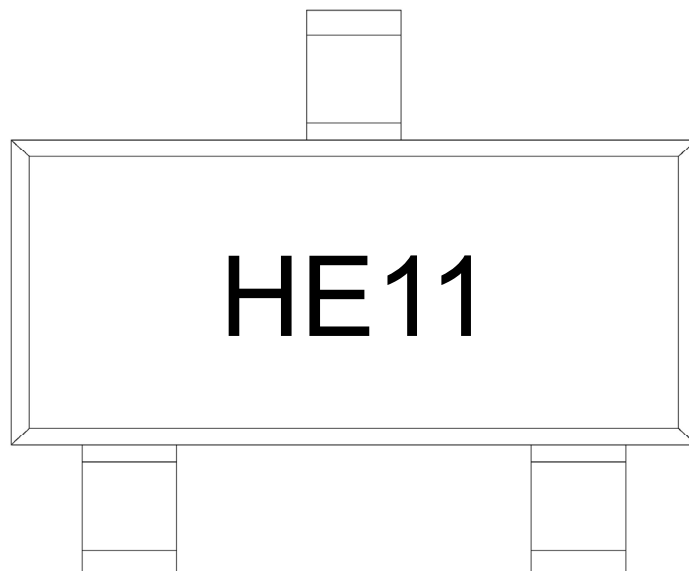
SOT-323

单位; mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	1.95	2.35	C	0.30	0.50
L	2.00	2.2	L1	0.85	1.15
E	1.20	1.40	a	0.20	0.40
B	1.15	1.35	P	7°	

印章说明 / Marking Instructions



说明：

H： 为公司代码

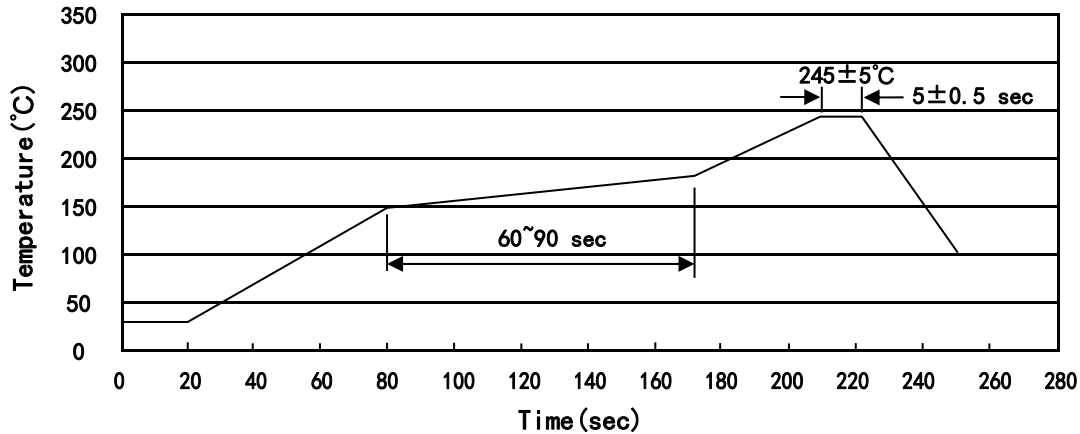
E11： 为型号代码

Note:

H： Company Code

E11： Product Type Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-323	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

**使用说明 / Notices**